

Application No.: 10/718,455

Docket No.:JCLA12114

In The Claims:

Please amend the claims as follows:

Claim 1. (currently amended) A frame-attaching package process adapted to attach an attaching surface of a transparent substrate to an active area of a chip by a frame sealant, the active area of the chip comprising a functional area, the frame-attaching package process comprising:

forming the frame sealant on the active area of the chip, the frame sealant surrounding the functional area;

placing the transparent substrate and the chip in a vacuum system and attaching the attaching surface of the transparent substrate to the frame sealant formed on the active area of the chip under a negative pressure; and

solidifying the frame sealant.

Claim 2. (currently amended) The frame-attaching package process of claim 1, wherein the negative pressure ranges from about 0.5 to about 0.9 atmospheres.

Claim 3. (currently amended) The frame-attaching package process of claim 1, wherein the step of solidifying the frame sealant is performed by exposing the frame sealant to an ultraviolet light.

Claim 4. (currently amended and withdrawn) A frame-attaching package process adapted to attach an attaching surface of a transparent substrate to an active area of a chip using a frame

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Application No.: 10/718,455

Docket No.:JCLA12114

sealant, the active area of the chip comprising a functional area, the frame-attaching package process comprising:

forming the frame sealant on the attaching surface of the transparent substrate;
placing the transparent substrate and the chip in a vacuum system and attaching the frame sealant formed on the attaching surface of the transparent substrate to the active area of the chip under a negative pressure, the frame sealant surrounding the functional area; and
solidifying the frame sealant.

Claim 5. (currently amended and withdrawn) The frame-attaching package process of claim 4, wherein the negative pressure ranges from about 0.5 to about 0.9 atmospheres.

Claim 6. (currently amended and withdrawn) The frame-attaching package process of claim 4, wherein the step of solidifying the frame sealant is performed by exposing the frame sealant to an ultraviolet light.

Claim 7. (currently amended) A frame-attaching package process adapted to attach an attaching surface of a transparent substrate to an active area of a chip using a frame sealant, the active area of the chip comprising a functional area, the frame-attaching package process comprising:

placing the transparent substrate and the chip in a vacuum system;
attaching the attaching surface of the transparent substrate to the active area of the chip using the frame sealant under a negative pressure, the frame sealant surrounding the functional area; and

Application No.: 10/718,455

Docket No.:JCLA12114

solidifying the frame sealant.

Claim 8. (currently amended) The frame-attaching package process of claim 7, further comprising forming the frame sealant on the active area of the chip before the step of attaching the transparent substrate to the active area of the chip.

Claim 9. (currently amended and withdrawn) The frame-attaching package process of claim 7, further comprising forming the frame sealant on the attaching surface of the transparent substrate before the step of attaching the transparent substrate to the active area of the chip.

Claim 10. (currently amended) The frame-attaching package process of claim 7, wherein the negative pressure ranges from about 0.5 to about 0.9 atmospheres.

Claim 11. (currently amended) The frame-attaching package process of claim 7, wherein the step of solidifying the frame sealant is performed by exposing the frame sealant to an ultraviolet light.